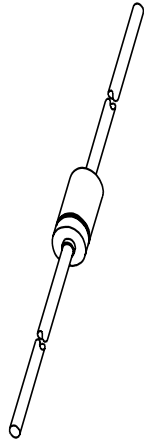


DATA SHEET



BAS45A Low-leakage diode

Product data sheet
Supersedes data of June 1994

1996 Mar 13

Low-leakage diode

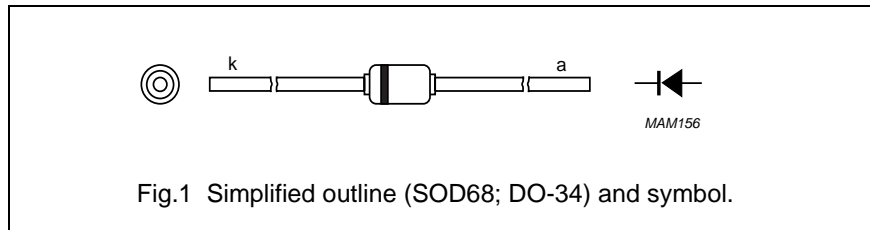
BAS45A

FEATURES

- Continuous reverse voltage: max. 125 V
- Repetitive peak forward current: max. 625 mA
- Low reverse current: max. 1 nA
- Switching time: typ. 1.5 μ s.

DESCRIPTION

Epitaxial medium-speed switching diode with a low leakage current in a hermetically-sealed glass SOD68 (DO-34) package.



APPLICATION

- Low leakage current applications.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	125	V
V_R	continuous reverse voltage		–	125	V
I_F	continuous forward current	see Fig.2; note 1	–	250	mA
I_{FRM}	repetitive peak forward current		–	625	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25\text{ }^\circ\text{C}$ prior to surge; see Fig.4 $t_p = 1\text{ }\mu\text{s}$ $t_p = 1\text{ ms}$ $t_p = 1\text{ s}$	–	4 1 0.5	A A A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ }^\circ\text{C}$	–	300	mW
T_{stg}	storage temperature		–65	+175	$^\circ\text{C}$
T_j	junction temperature		–	175	$^\circ\text{C}$

Note

1. Device mounted on a printed-circuit board without metallization pad.

Low-leakage diode

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ELECTRICAL CHARACTERISTICST_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	see Fig.3 I _F = 1 mA I _F = 10 mA I _F = 100 mA	– – –	780 860 1000	mV mV mV
I _R	reverse current	see Fig.5 V _R = 125 V; E _{max} = 100 lx V _R = 30 V; T _j = 125 °C; E _{max} = 100 lx V _R = 125 V; T _j = 125 °C; E _{max} = 100 lx V _R = 125 V; T _j = 150 °C; E _{max} = 100 lx	– – – –	1 300 500 2	nA nA nA μA
C _d	diode capacitance	f = 1 MHz; V _R = 0; see Fig.6	–	4	pF
t _{rr}	reverse recovery time	when switched from I _F = 10 mA to I _R = 10 mA; R _L = 100 Ω; measured at I _R = 1 mA; see Fig.7	1.5	–	μs

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	8 mm from the body	300	K/W
R _{th j-a}	thermal resistance from junction to ambient	lead length 10 mm; note 1	500	K/W

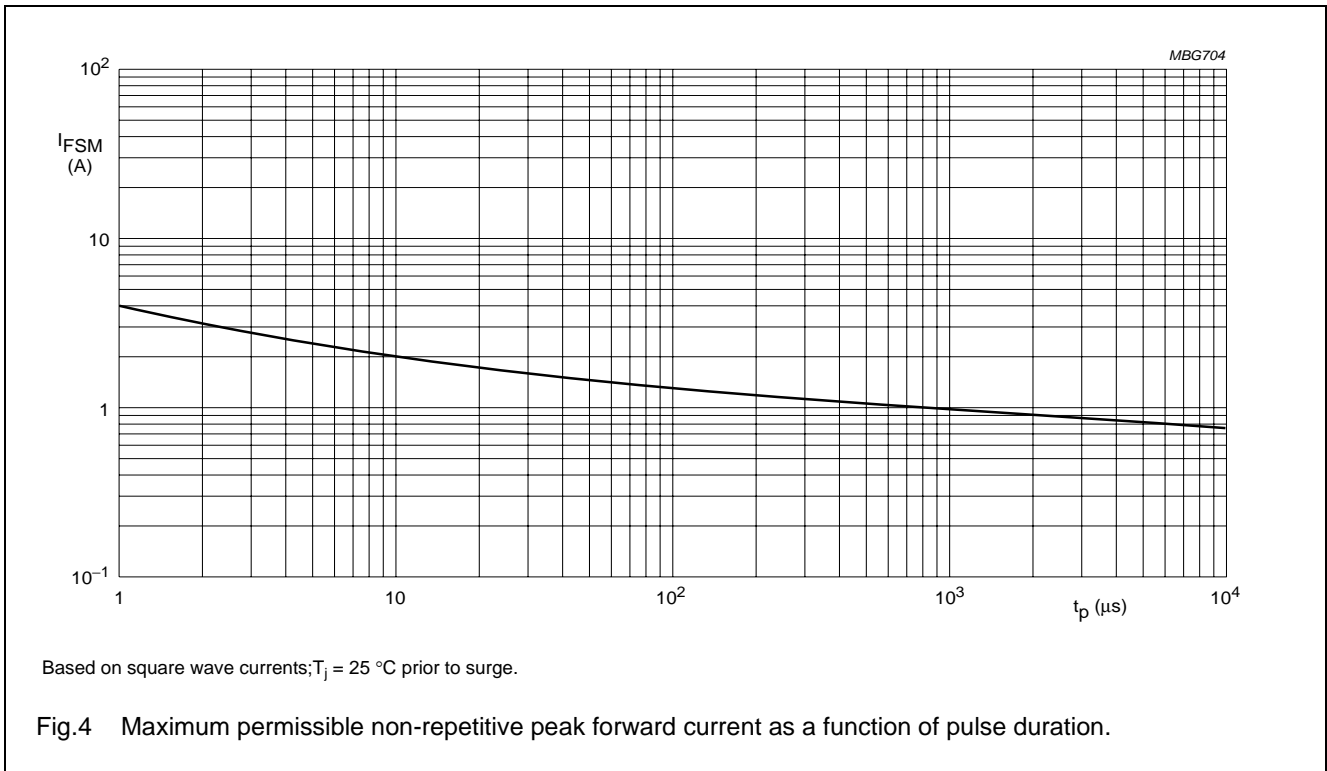
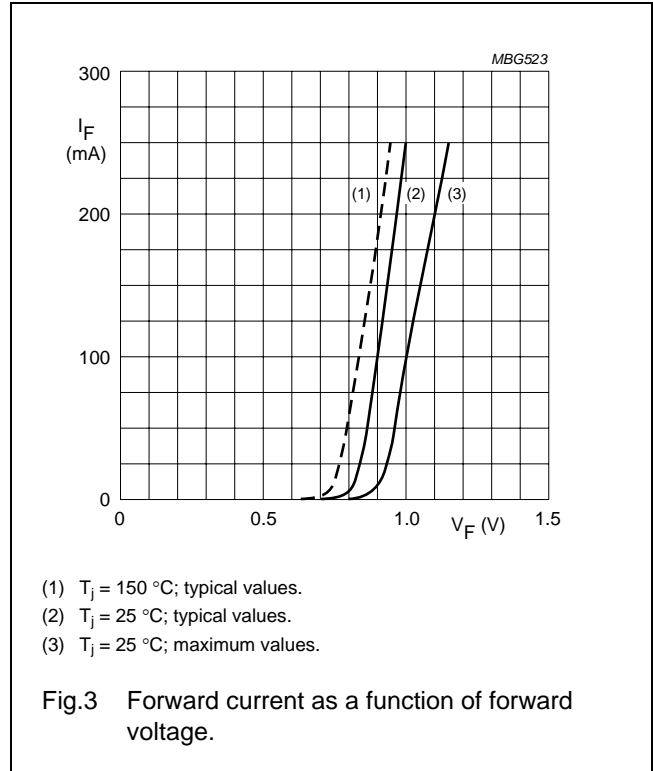
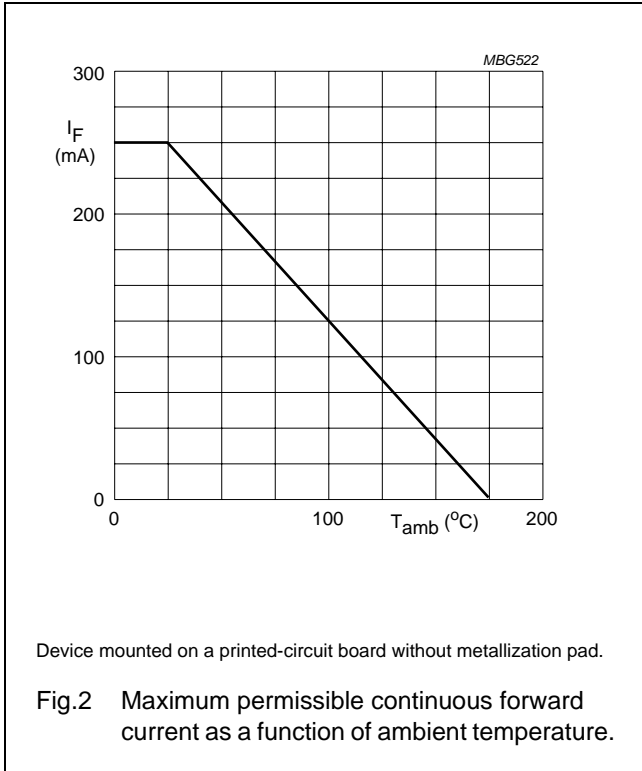
Note

1. Device mounted on a printed-circuit board without metallization pad.

Low-leakage diode

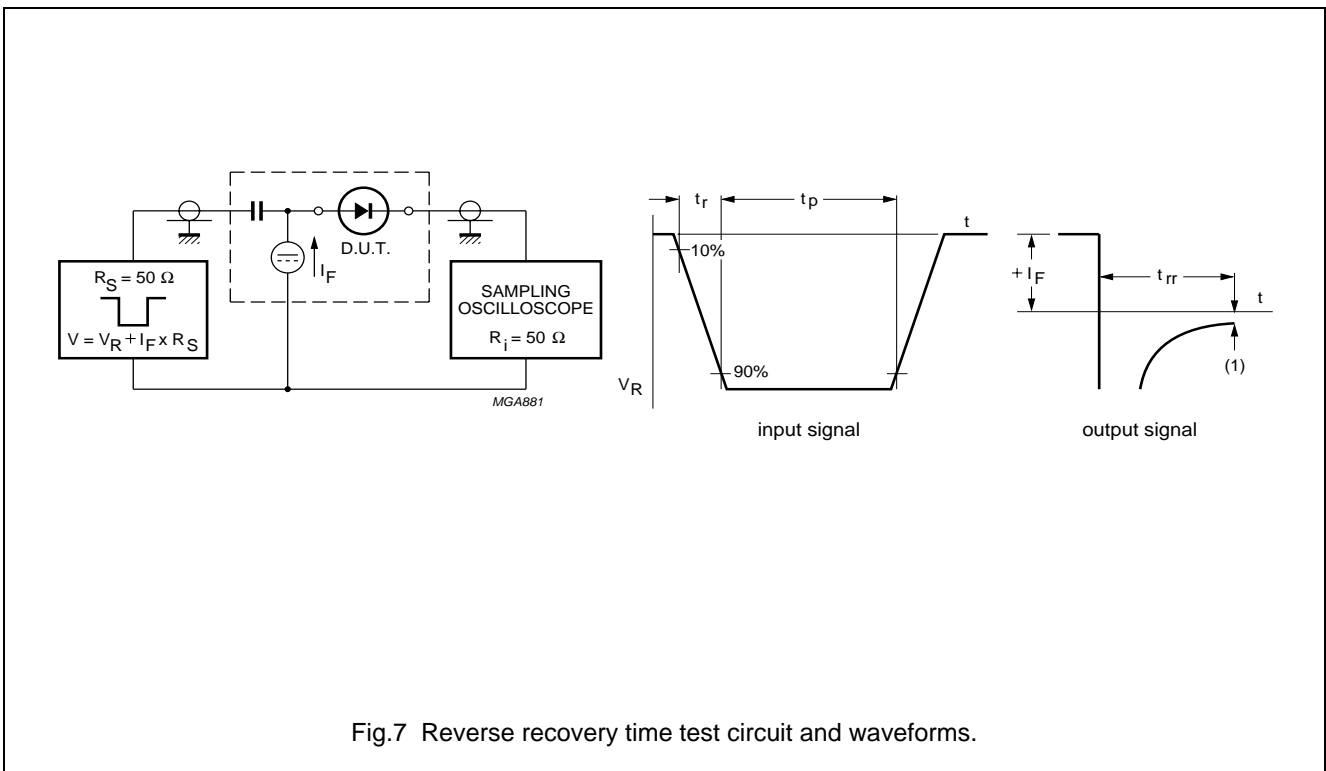
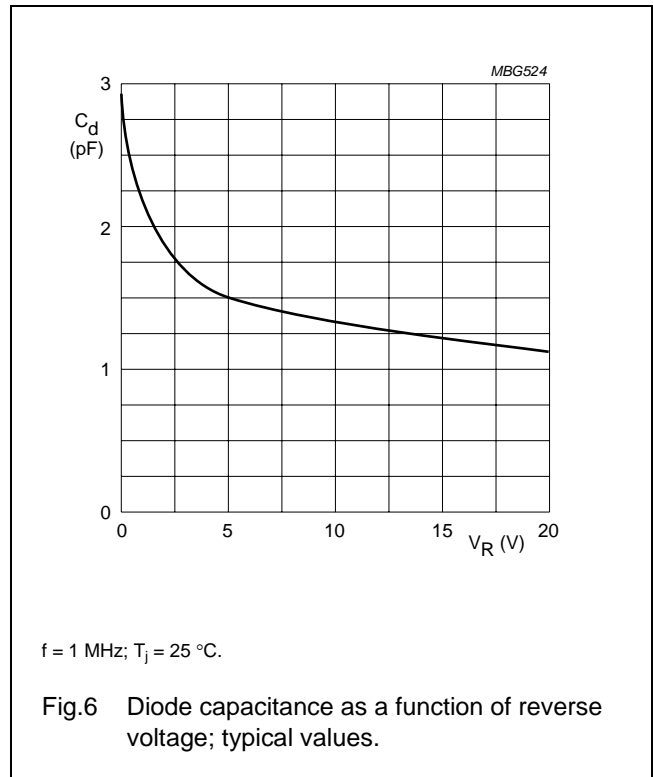
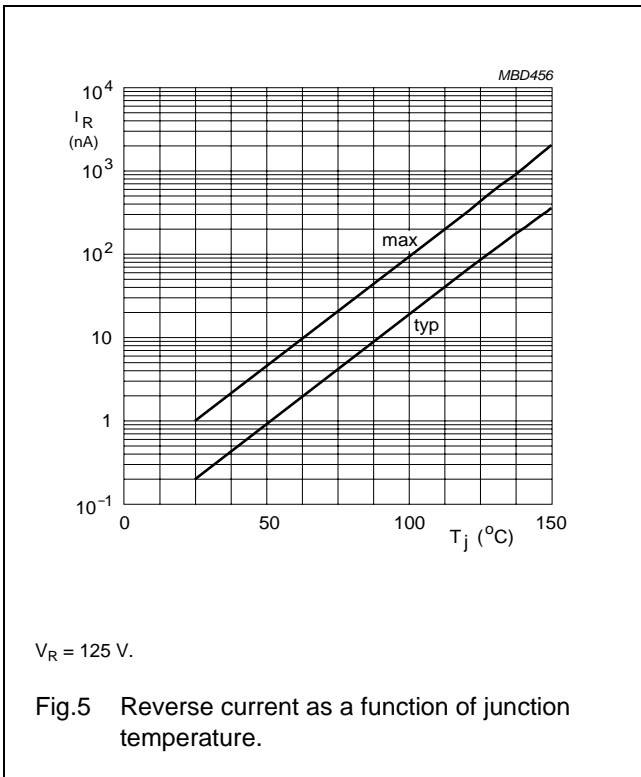
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GRAPHICAL DATA



Low-leakage diode

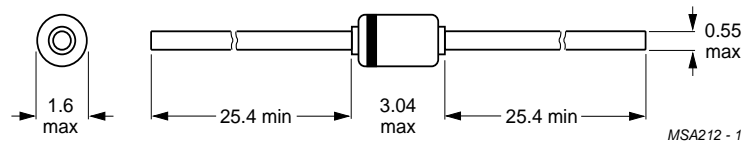
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Low-leakage diode

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PACKAGE OUTLINE



Dimensions in mm.
The black marking band indicates the cathode.

Fig.8 SOD68 (DO-34).

Low-leakage diode

BAS45A

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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